

METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD
SEMICONDUCTOR PACKAGED DEVICES

ABSTRACT OF THE DISCLOSURE

A semiconductor package structure for a ball grid array type package using a plurality of pieces of adhesive elastomer film to attach a semiconductor die to a substrate having conductive traces in order to alleviate thermal mismatch stress between the semiconductor die and the printed circuit board to which the packaged device is soldered, while maintaining the reliability of the packaged device itself.

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